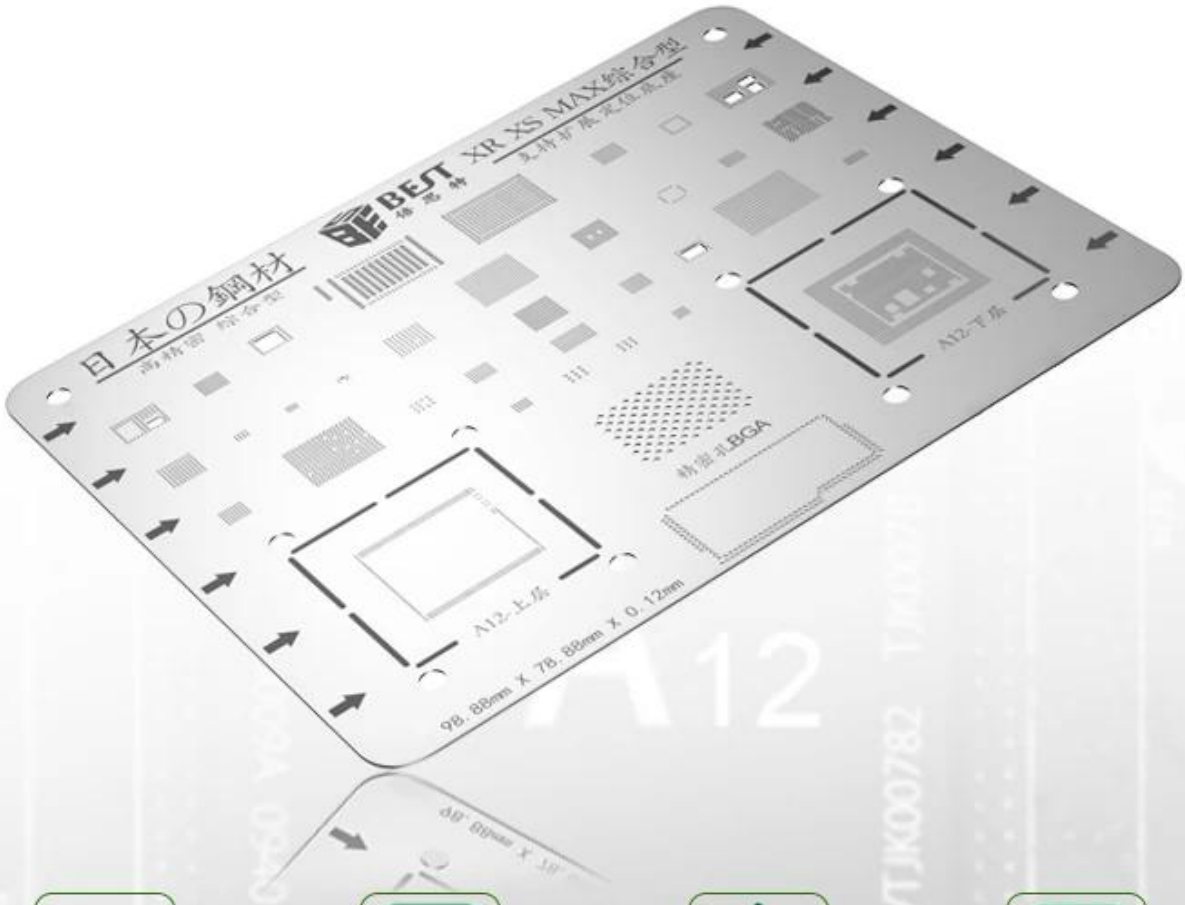
REBALLING STENCIL

— iPhone CPU series —



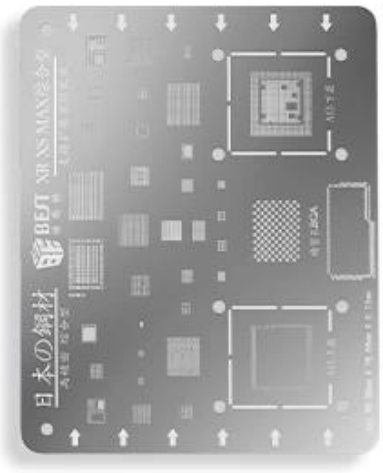
SEMI-ETCHING PROCESS

COOLING HOLE DESIGN

PRECISE ALIGNMENT

SQUARE HOLE

Product Usage



MATERIAL	Imported steel
BRAND	BESTOOL
PRODUCT NAME	Reballing Stencil
WEIGHT	7g /3.8g
TYPE	Precise alignment Strong toughness Non-stick ti

▼PRODUCT CHARACTIERISTICS

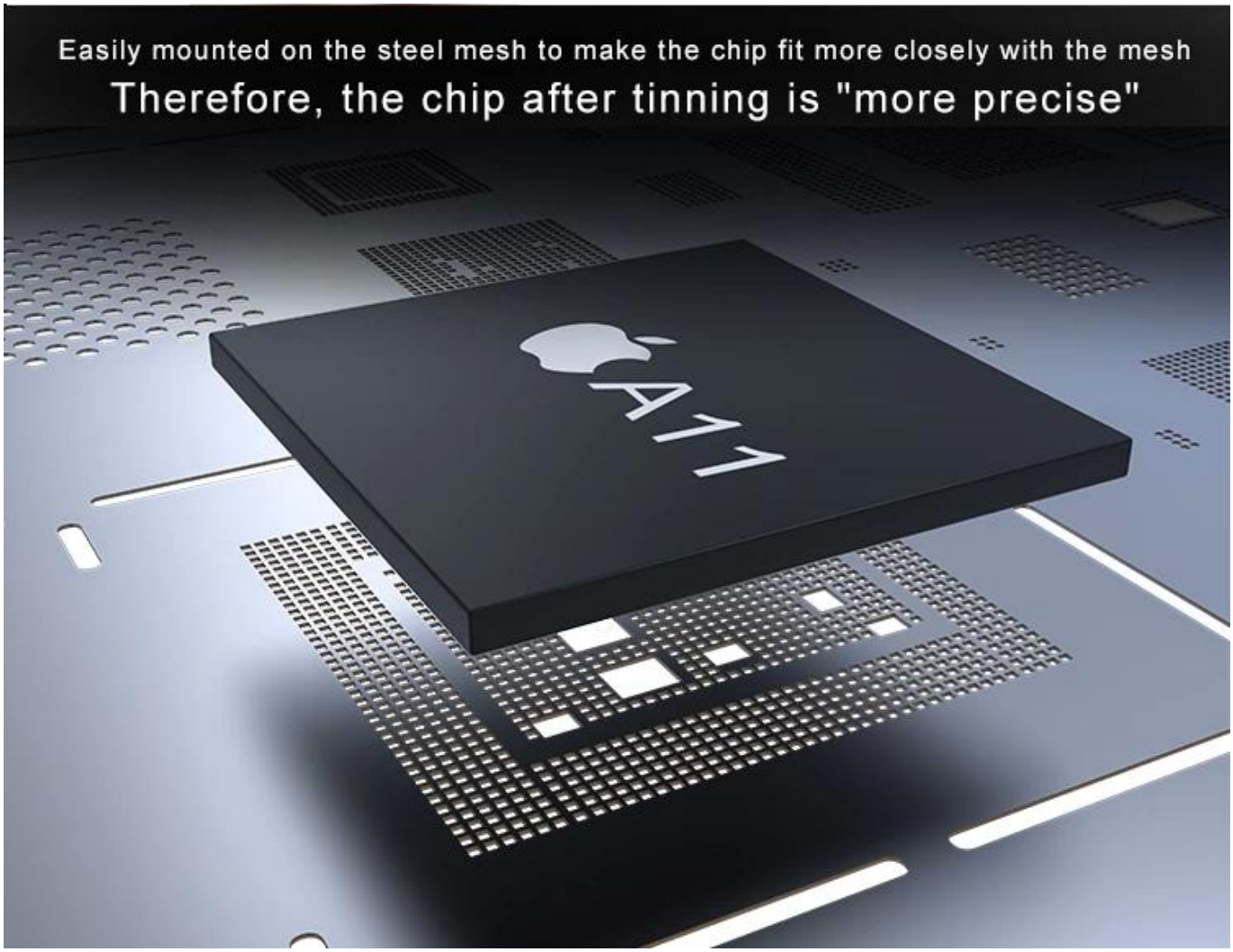
This product is used for BGA tinning repair of iPhone series. It adopts imported steel material, anti-rolling anti-deformation, automatic alignment, precise hole position, non-stick tin, good toughness and off-grid.

PRODUCT INFORMATION

IMPORTED STEEL

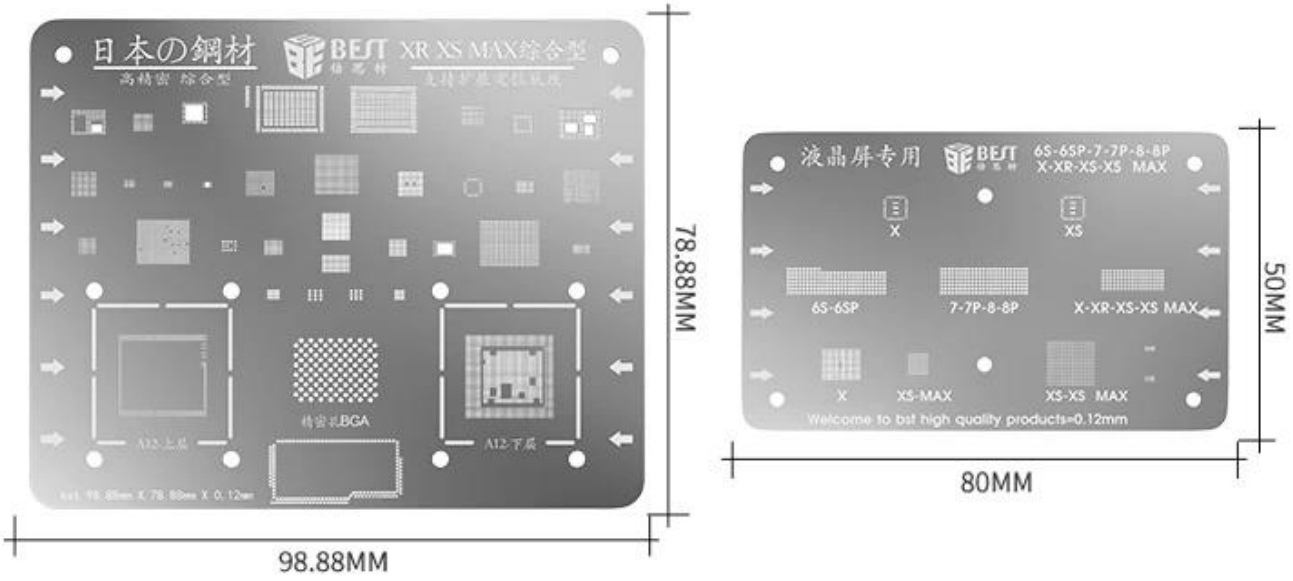
HIGH TOUGHNESS

GOOD PRODUCTS ARE NOT ONLY
EXCELLENT FORGING PROCESSES,
BUT THE REAL CORE LIES IN THE
SELECTION OF DELICATE MATERIALS.


Easily mounted on the steel mesh to make the chip fit more closely with the mesh
Therefore, the chip after tinning is "more precise"
A11

Imported steel
Hard and wear resistant
Accurate to the hole

PRODUCT SIZE

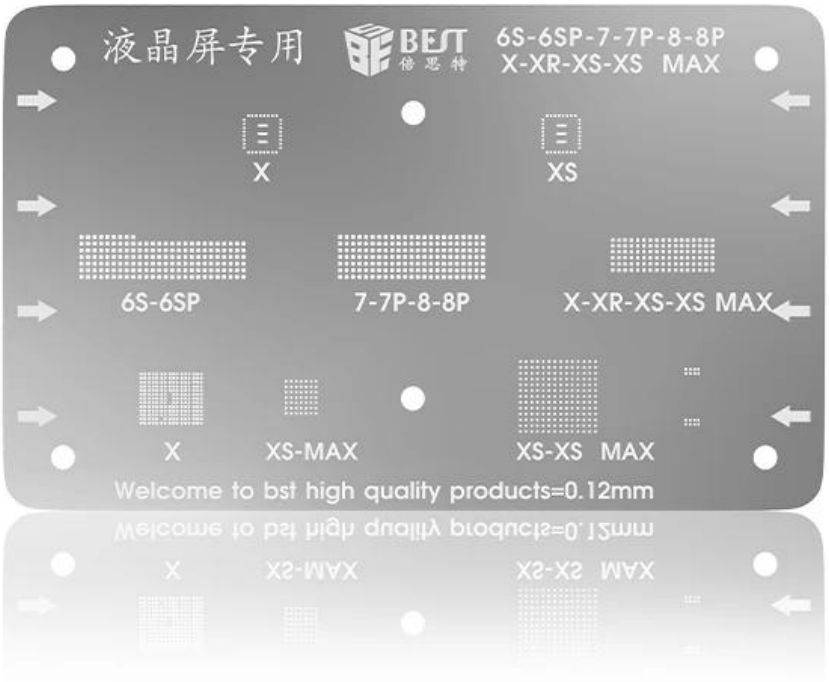


Thin to 0.12mm

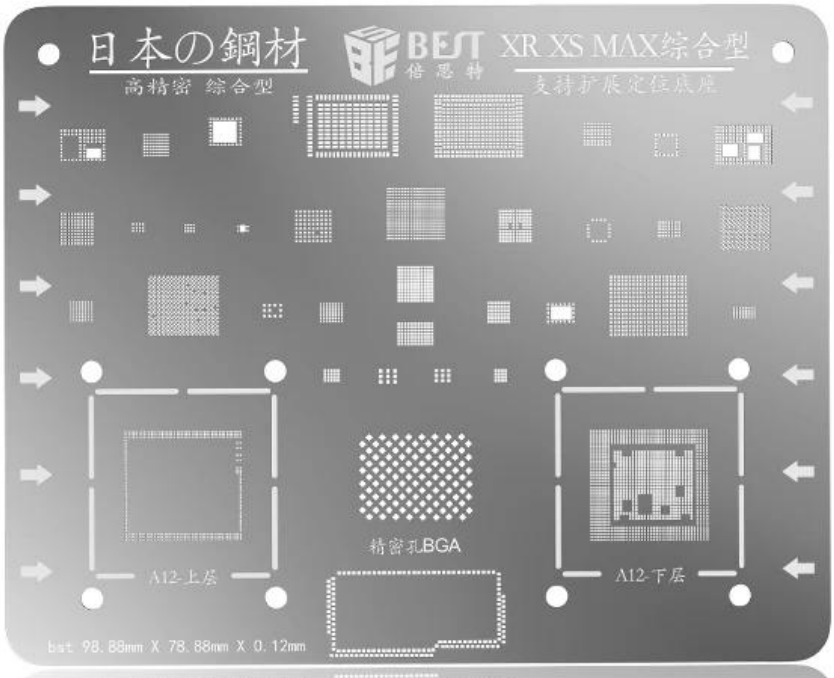
Precise die-casting Iform heating

0.12
OFF/ON
ZERO
70
80
90
100
110
120

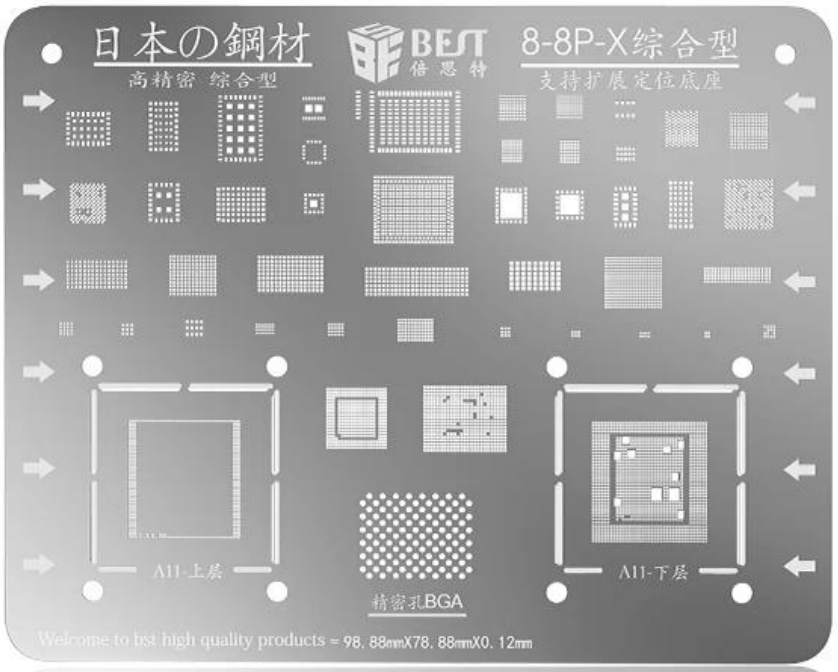
6S-6SP-7-7P-8-8P-X-XR-XS-XS MAX



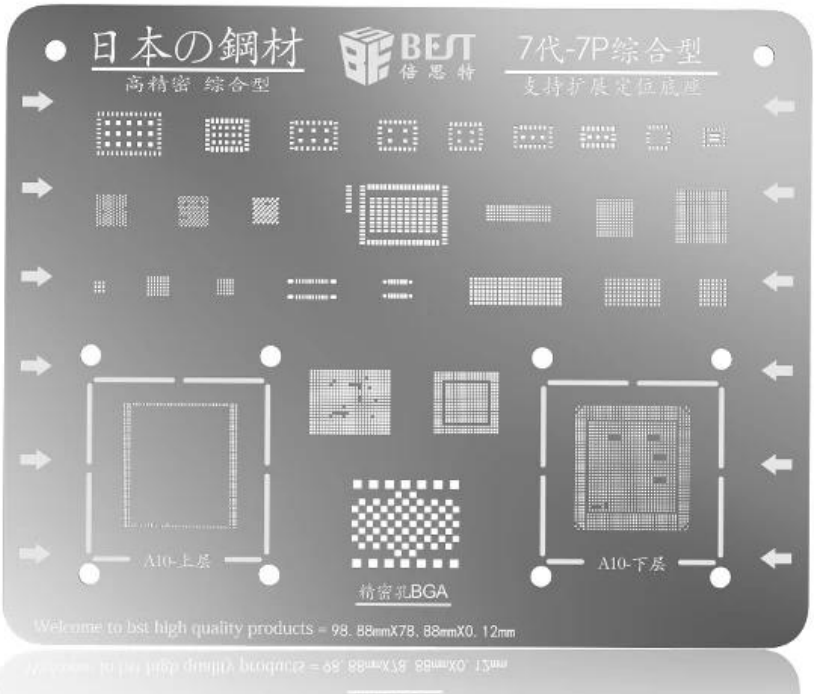
XR-XS-XS MAX COMPREHENSIVE



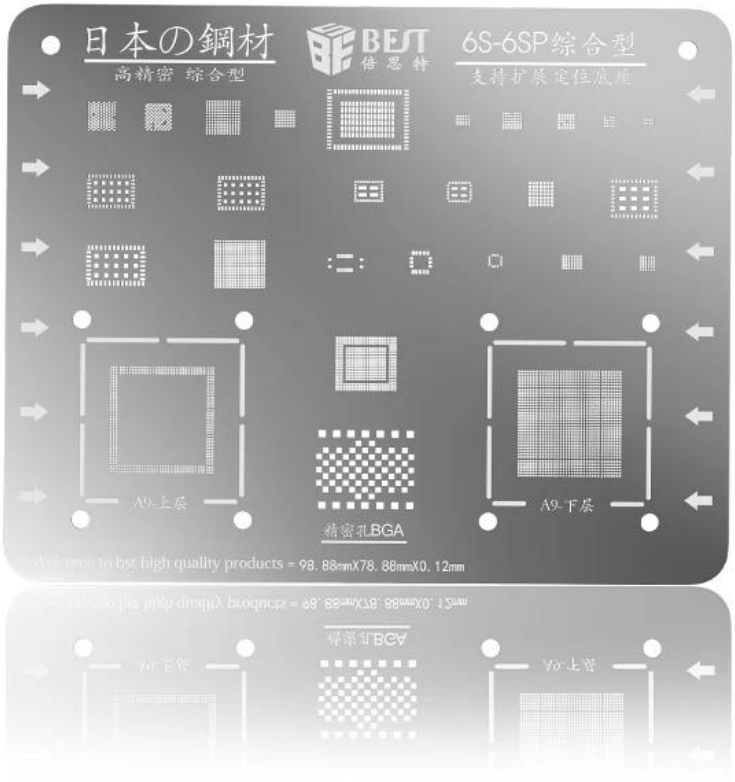
8-8P-X COMPREHENSIVE



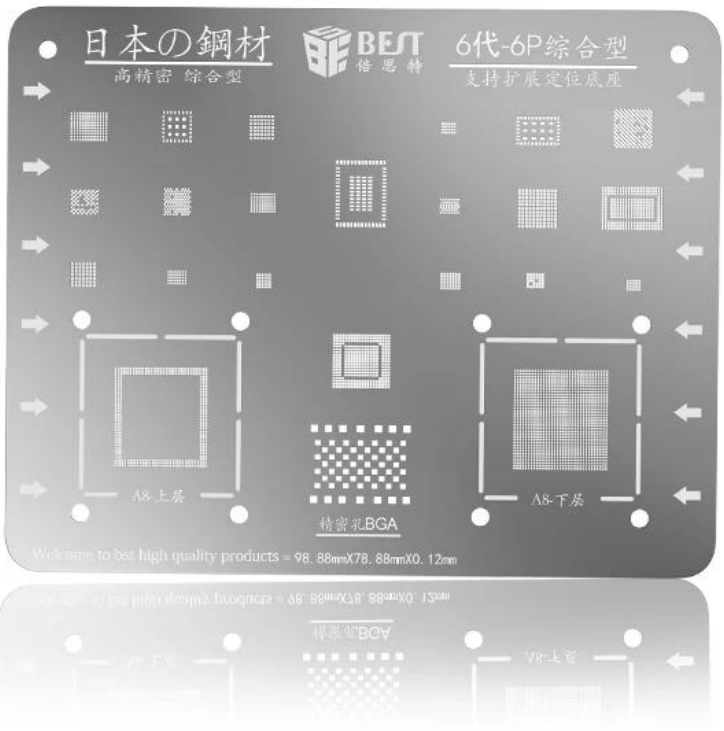
7-7P COMPREHENSIVE

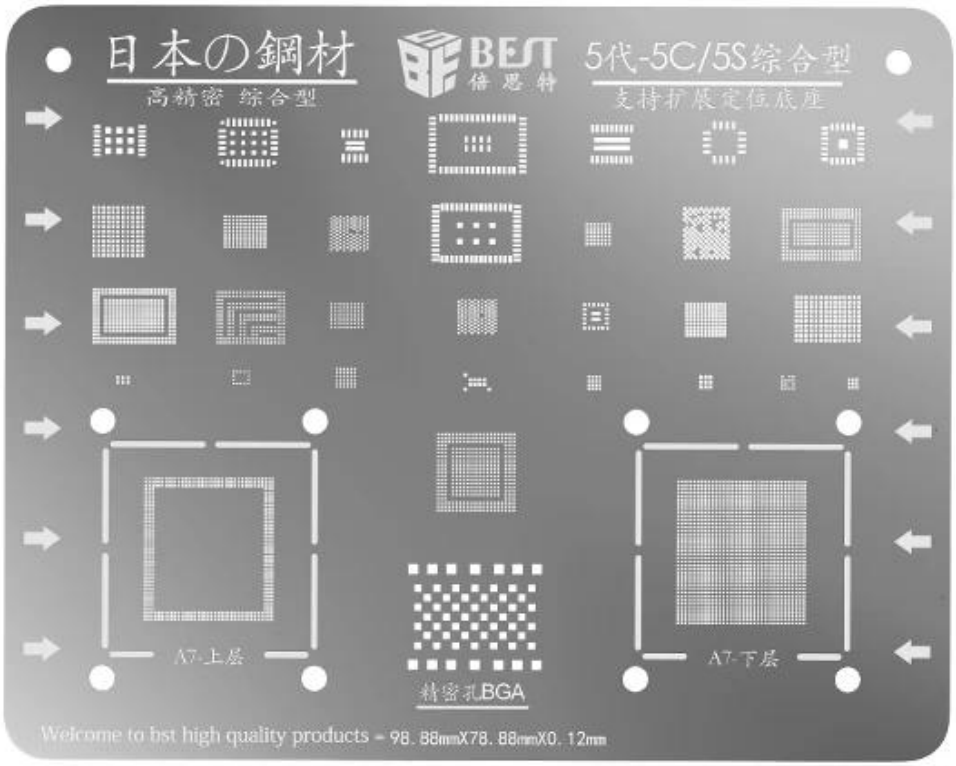


6S-6SP COMPREHENSIVE



6-6P COMPREHENSIVE

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高精密 综合型
BEST
倍思特
5代-5C/5S综合型
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精密孔BGA
A7-下层
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